









B1D20120H

1200V A 20A A SIC SCHOTTKY DIODE

SILICON CARBIDE SIC SCHOTTKY DIODE ▲ THT type

Excellent surge capability
Easy paralleling due to positive V_F temperature coefficient

TO-247-2L package ▲ Epoxy meets UL94-V0

Low forward voltage

Temperature independent switching

Item (T _C = 25°C, unless otherwise noted)		Characteristics
Operating Temperature Range	T _J	-55°C to +175°C
Storage Temperature Range	Ts	-55°C to +175°C
Repetitive Peak Reverse Voltage	V_{RRM}	1200V
Continuous Forward Current at T _C = 160°C	I _F	20A
Total Capacitive Charge (T _J = 25°C)	\mathbf{Q}_{c}	101nC
Capacitance Stored Energy (V _R = 800V)	E c	52µJ
Diode Forward Voltage (T _J = 175°C, I _F = 20A)	V_{F}	1.9V
Power Dissipation	P _{TOT}	269W

APPLICATIONS

EV Charging	Industrial Inverters	Motors & Drives	Power Factor Correction	Renewable Energy	SMPS	UPS
∳ / /=			PFC	*		

PIN DESCRIPTION

Circuit Diagram	Outline • Front View	Pin No.	Description
Backside 0 1 2		1 2	Cathode (Backside) Anode

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ABSOLUT MAXIMUM RATINGS ▲ T_C = 25°C, unless otherwise noted

Item	Condition	Symbol		Unit
Repetitive Peak Reverse Voltage		V_{RRM}	1200	V
Non-Repetitive Peak Reverse Voltage		V_{RSM}	1200	V
Continuous Forward Current	T _C = 25°C	I _F	60	Α
Continuous Forward Current	$T_{C} = 150^{\circ}C$	I _F	20	Α
Non-Repetitive Forward Surge Current	T_C = 25°C, t_p = 10ms, Half Sine Wave	I _{FSM}	150	Α
I ² t Value	$T_C = 25^{\circ}C$, $t_p = 10$ ms	∫i²dt	112.5	A^2s
Power Dissipation	T _C = 25°C	P _{TOT}	269	W
Power Dissipation	$T_C = 110^{\circ}C$	P_{TOT}	116	W
Operating Junction Temperature		TJ	-55 to +175	°C
Storage Temperature Range		T_{STG}	-55 to +175	°C
TO-247 Mounting Torque	M3 Screw		0.7	Nm

ELECTRICAL CHARACTERISTICS

Item	Condition	Symbol	Min.	Тур.	Max.	Unit
Static Characteristics						
DC Blocking Voltage	T _J = 25°C	V_{DC}	1200			V
Diode Forward Voltage	$I_F = 20A, T_J = 25^{\circ}C$	V_{F}		1.46	1.61	V
Diode Forward Voltage	$I_F = 20A, T_J = 175^{\circ}C$	V_{F}		1.90	2.35	V
Reverse Current	$V_R = 1200V, T_J = 25^{\circ}C$	I _R		10	120	μΑ
Reverse Current	V _R = 1200V, T _J = 175°C	I _R		40	400	μΑ
Item	Condition	Symbol	Min.	Тур.	Max.	Unit
Dynamic Characteristics						•
,						
,	$V_R = 800V, T_J = 25^{\circ}C$					
Total Capacitive Charge	$V_{R} = 800V, T_{J} = 25^{\circ}C$ $Q_{C} = \int_{0}^{V_{R}} C(V) dV$	Qc		101		nC
		Q _c		101 1170		nC pF
Total Capacitive Charge	$Q_C = \int_0^{V_R} C(V) dV$					
Total Capacitive Charge Total Capacitance	$Q_C = \int_0^{V_R} C(V) dV$ $V_R = 1V, f = 1MHz, T_J = 25^{\circ}C$	С		1170		pF

THERMAL RESISTANCE PERFORMANCE

Item	Symbol	Min.	Тур.	Max.	Unit
Thermal Resistance, Junction to Case	$R_{\theta,JC}$		0.557		K/W



REFERENCE DATA A TYPICAL PERFORMANCE

Fig. 1 - Typical Forward Characteristics IF vs. VF

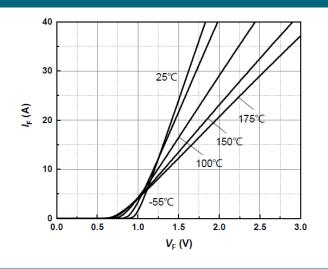


Fig. 2 • Typical Reverse Current I_R as function of Reverse Voltage V_R

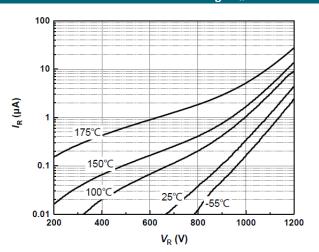


Fig. 3 • Diode Forward Current I_F as function of Case Temperature T_C (D = Duty Cycle)

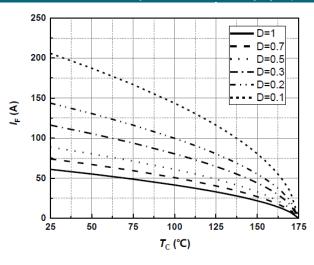


Fig. 4 • Typical Capacitance C as function of Reverse Voltage V_R , $C = f(V_R)$, $T_J = 25^{\circ}C$, f = 1MHz

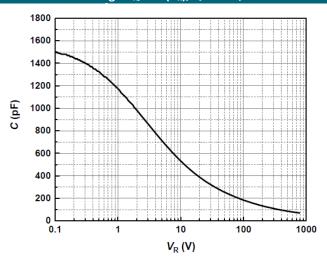


Fig. 5 • Typical Reverse Charge Q_C as function of Reverse Voltage V_R

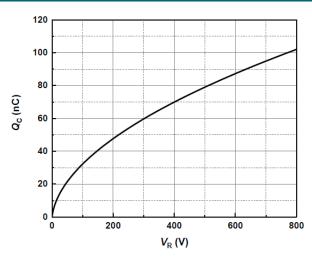
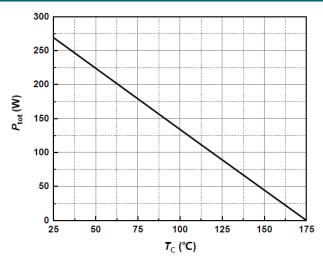


Fig. 6 • Power Dissipation P_{TOT} as function of Case Temperature T_c



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REFERENCE DATA A TYPICAL PERFORMANCE

Fig. 7 - Capacitance Stored Energy

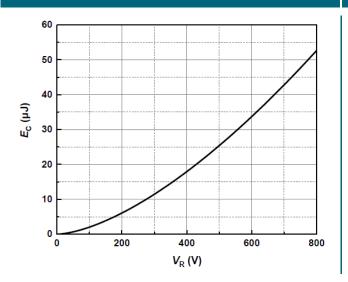
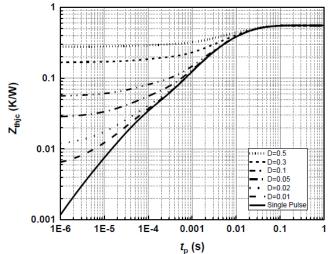
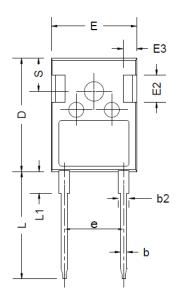


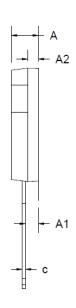
Fig. 8 • Maximum Transient Thermal Impedance, Z_{thjc} = f(t), Parameter: D = t/T

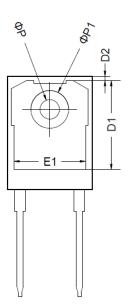




PACKAGE OUTLINE









Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)
Α	4.80	5.00	5.20
A1	2.21	2.41	2.61
A2	1.85	2.00	2.15
b	1.11	1.21	1.36
b2	1.91	2.01	2.21
С	0.51	0.61	0.75
D	20.80	21.00	21.30
D1	16.25	16.55	16.85
D2	1.05	1.17	1.35
E	15.50	15.80	16.10

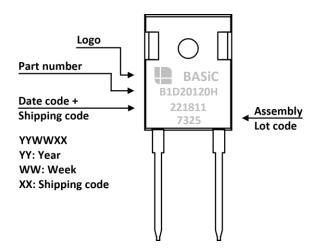
Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)		
E1	13.00	13.30	13.60		
E2	4.80	5.00	5.20		
E3	2.30	2.50	2.70		
e	10.88 BSC				
L	19.62	19.92	20.22		
L1	-	-	4.30		
ØΡ	3.40	3.60	3.80		
ØP1	-	-	7.30		
S		6.15 BSC			

ORDERING INFORMATION

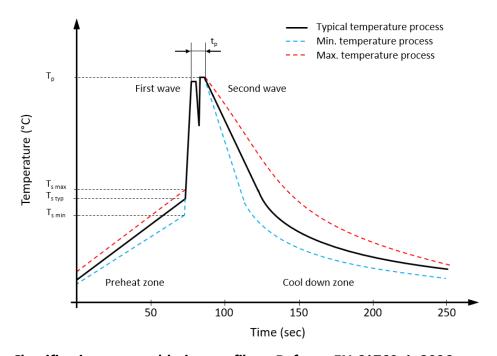
Part Number	Package	Packing	Tube Qty.	Inner Box Qty.	Outer Box Qty.
B1D20120H	TO-247-21	Tube	30ncs	600pcs	3.000pcs



PART MARKING



RECOMMENDED WAVE SOLDERING PROFILE & THT PACKAGE



Classification wave soldering profile ▲ Refer to EN 61760-1: 2006

Profile Features		Value ▲ Sn-Pb Assembly	Value ▲ Pb-free Assembly
Preheat temperature min.	T_{smin}	100 °C	100 °C
Preheat temperature typical	T _{s typ}	120 °C	120 °C
Preheat temperature max.	T_{smax}	130 °C	130 °C
Preheat time t_s from T_{smin} to T_{smax}	ts	70 seconds	70 seconds
Peak temperature	T_p	235 °C to 260 °C	245 °C to 260 °C
Time of actual peak temperature	tp	Max. 10 seconds Max. 5 second each wave	Max. 10 seconds Max. 5 second each wave
Ramp-down date min.		~ 2 °C/second	~ 2 °C/second
Ramp-down rate typical		~ 3.5 °C/second	~ 3.5 °C/second
Ramp-down rate max.		~ 5 °C/second	~ 5 °C/second
Time 25°C to 25°C		4 minutes	4 minutes

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REVISION TABLE

Revision	Date	Status	Notes
001	30/09/2022	Initial release	Initial publication

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